

**RJ45C5 R1U 2.8N4N RL****Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com



The product range encompasses the following designs:

- 90°, lying (horizontal) and 180°, standing (vertical)
- latch up / latch down
- THT, THR or SMD soldering processes
- Wide range of different design types, also with integrated LEDs and shield contact tabs
- Performance category Cat. 3 to Cat. 6
- Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
- Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
- Dielectric strength  $\geq 1500$  V AC RMS (2250 V AC peak value) according to IEEE 802.3
- Dielectric strength  $\geq 1500$  V AC (peak value) or  $\geq 1500$  V DC according to IEC 60603

Properties and advantages:

- Extended temperature range of  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  for maximum performance
- Reinforced gold layer ( $30\mu\text{m}$ ) for improved corrosion protection
- At least 0.3mm stand-off ensures a perfect soldering result

**General ordering data**

Version	PCB plug-in connector, RJ45 jacks, Cat. 5 , THT/THR solder connection, 90°, Latch option: top, Shield tabs: none, $30\ldots 80\mu\text{m}$ / $\geq 30\mu\text{m}$ , LED: No, Number of poles: 8, Tape
Order No.	<a href="#">2638490000</a>
Type	RJ45C5 R1U 2.8N4N RL
GTIN (EAN)	4050118657104
Qty.	200 pc(s).
Packaging	Tape

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## Technical data

## Dimensions and weights

Depth	15.7 mm	Depth (inches)	0.618 inch
Height	13.11 mm	Height (inches)	0.516 inch
Width	16.4 mm	Width (inches)	0.646 inch
Net weight	7.095 g		

## System specifications

Category	Cat. 5	LED	No
Latch option	top	Mounting onto the PCB	THT/THR solder connection
Number of poles	8	Outgoing elbow	90°
Performance-Category	Cat. 5	Pitch in inches (P)	0.04 "
Pitch in mm (P)	1.02 mm	Plugging cycles	750
Product family	OMNIMATE Data - RJ45 modular jack	Protection degree	IP20
Shield surface	nickel-plated	Shield tabs	none
Shielding	Yes	Shielding material	Brass, nickel-plated
Solder pin dimensions	Octagonal	Solder pin length (l)	2.8 mm
Soldering process	Reflow soldering, Manual soldering, Wave soldering	Tolerance of solder pin position	± 0.1 mm
Type of connection	Solder connection		

## Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC
Insulation strength	≥ 500 MΩ	PoE / PoE+	conforming to IEEE 802.3at
Rated current	1.5 A	Rated voltage	125 V

## Standards

Connector standard	IEC 60603-7
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## Material data

Insulating material	PA 9T	Colour	black, Cyan
Colour chart (similar)	RAL 9011, RAL 5018	Insulating material group	II
Insulation strength	≥ 500 MΩ	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact base material	Phosphor bronze alloy
Contact material	Cu-alloy	Contact surface	Gold over nickel
Layer structure of solder connection	30...80 μ"	Layer structure of plug contact	30...80 μ" / ≥ 30 μ"
Storage temperature, min.	-40 °C	Storage temperature, max.	85 °C
Operating temperature, min.	-40 °C	Operating temperature, max.	85 °C

## Packing

Packaging	Tape	VPE length	357 mm
VPE width	354 mm	VPE height	126 mm

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ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01

**Approvals**

ROHS	Conform
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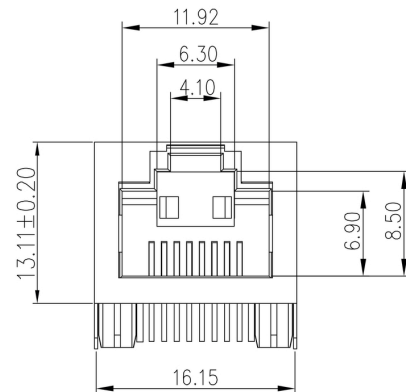
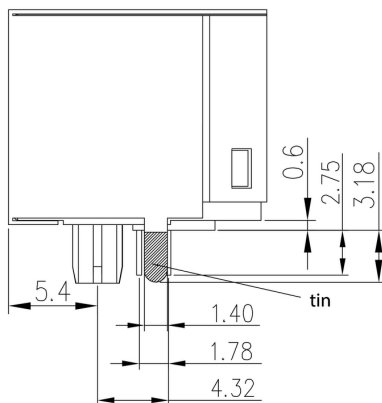
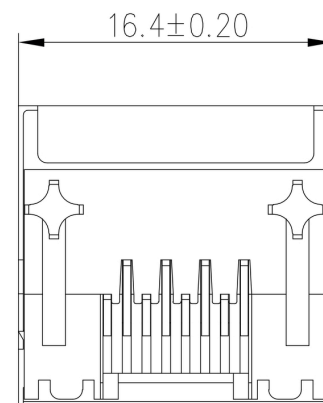
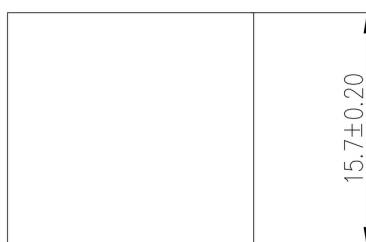
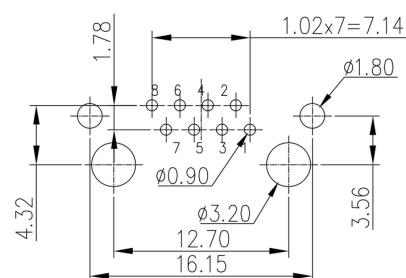
**Downloads**

Approval/Certificate/Document of Conformity	<a href="#">Certificate of Compliance</a>
Engineering Data	<a href="#">CAD data – STEP</a>
Catalogues	<a href="#">Catalogues in PDF-format</a>

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**Drawings**
**Dimensioned drawing**

**Dimensioned drawing**

**Dimensioned drawing**

**Dimensioned drawing**

**PCB design**




## Recommended wave soldering profiles

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Fax: +49 5231 14-292083  
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### Single Wave:



### Double Wave:



### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

## Recommended reflow soldering profile

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## Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3\text{K/s}$ . In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq -6\text{K/s}$  solder is cured. Board and components cool down while avoiding cold cracks.